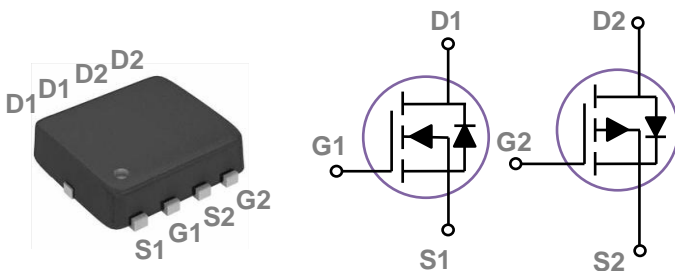


General Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK2.8X2.9 Dual NEP Pin Configuration



BVDSS	RDSON	ID
30V	14mΩ	10A
-30V	36mΩ	-6A

Features

- Fast switching
- Green Device Available
- Suit for 4.5V Gate Drive Applications

Applications

- DC Fan
- Motor Drive Applications
- Networking
- Half / Full Bridge Topology

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating		Units
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
I_D	Drain Current – Continuous ($T_A=25^\circ\text{C}$)	10	-6	A
	Drain Current – Continuous ($T_A=70^\circ\text{C}$)	8	-4.8	A
I_{DM}	Drain Current – Pulsed ¹	40	-24	A
P_D	Power Dissipation ($T_A=25^\circ\text{C}$)	2.5		W
	Power Dissipation – Derate above 25°C	0.02		W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150		$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150		$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	50	$^\circ\text{C}/\text{W}$

N-CH Electrical Characteristics (T_J=25 °C, unless otherwise)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =30V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =24V, V _{GS} =0V, T _J =125°C	---	---	10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =10A	---	11.7	14	mΩ
		V _{GS} =4.5V, I _D =8A	---	15	20	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.6	2.5	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =3A	---	6	---	S

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{2, 3}	V _{DS} =15V, V _{GS} =10V, I _D =5A	---	11	17	nC
Q _{gs}	Gate-Source Charge ^{2, 3}		---	1.4	2	
Q _{gd}	Gate-Drain Charge ^{2, 3}		---	2.7	4.5	
T _{d(on)}	Turn-On Delay Time ^{2, 3}	V _{DD} =15V, V _{GS} =10V, R _G =6Ω I _D =5A	---	3.8	7	ns
T _r	Rise Time ^{2, 3}		---	10	19	
T _{d(off)}	Turn-Off Delay Time ^{2, 3}		---	22	42	
T _f	Fall Time ^{2, 3}		---	6.6	13	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, F=1MHz	---	710	1065	pF
C _{oss}	Output Capacitance		---	100	150	
C _{rss}	Reverse Transfer Capacitance		---	80	120	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	---	3.2	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	10	A
I _{SM}	Pulsed Source Current		---	---	20	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V
T _{rr}	Reverse Recovery Time	V _R =30V, I _S =2A	---	360	---	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs, T _J =25°C	---	810	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

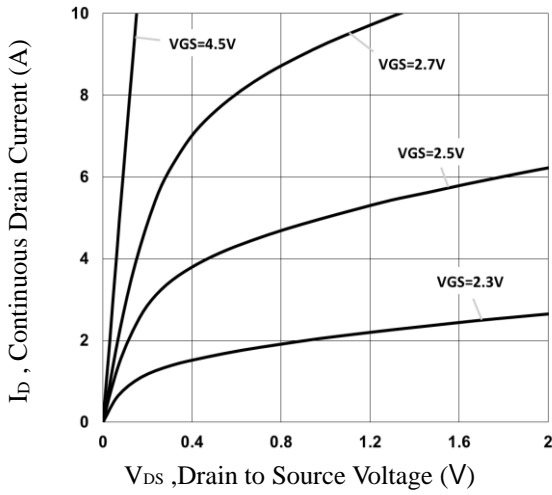


Fig.1 Typical Output Characteristics

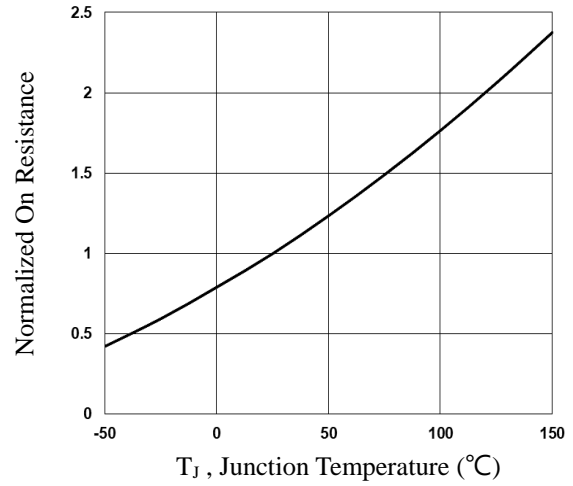


Fig.2 Normalized RDS(on) vs. T_J

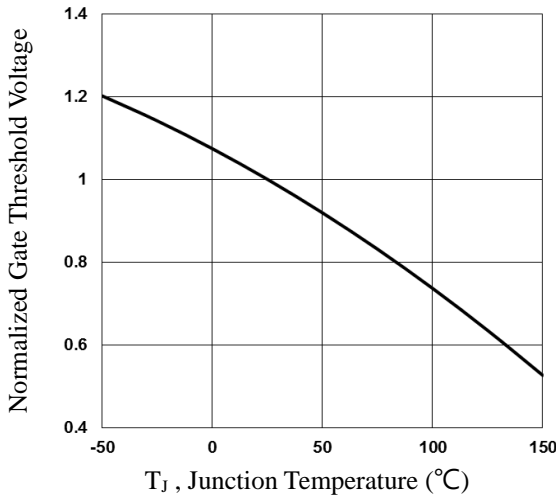


Fig.3 Normalized V_{th} vs. T_J

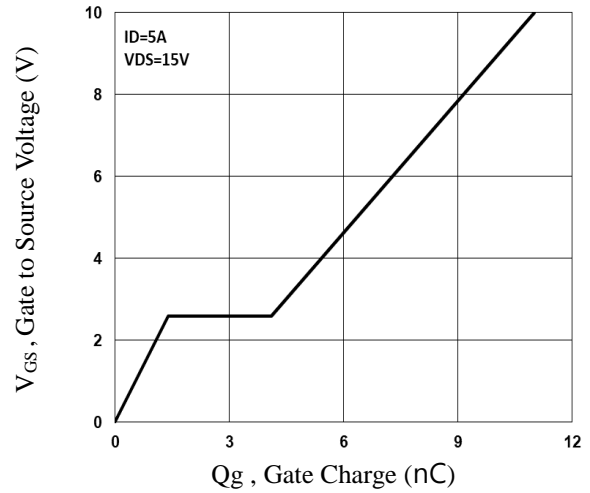


Fig.4 Gate Charge Waveform

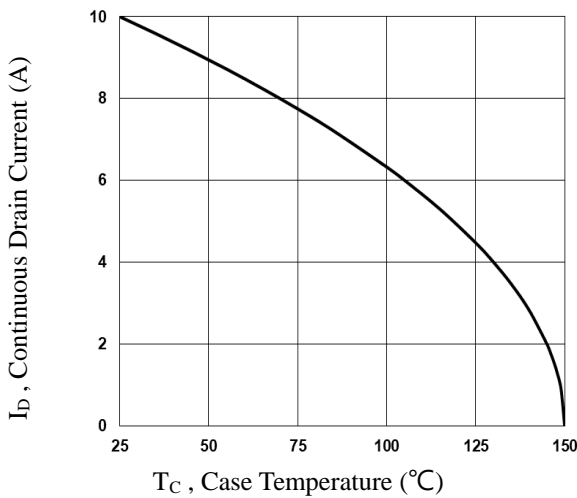


Fig.5 Continuous Drain Current vs. T_C

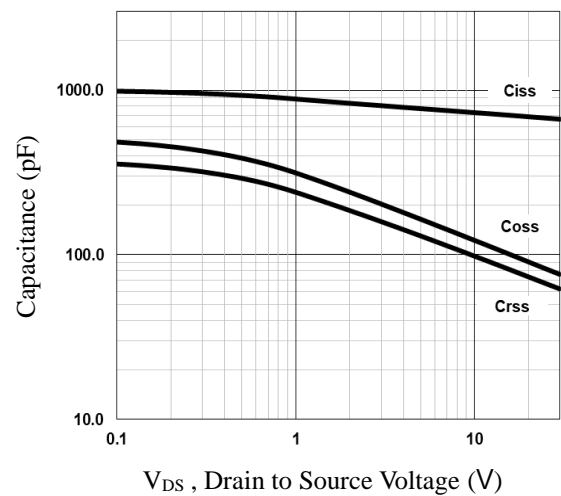


Fig.6 Capacitance Characteristics

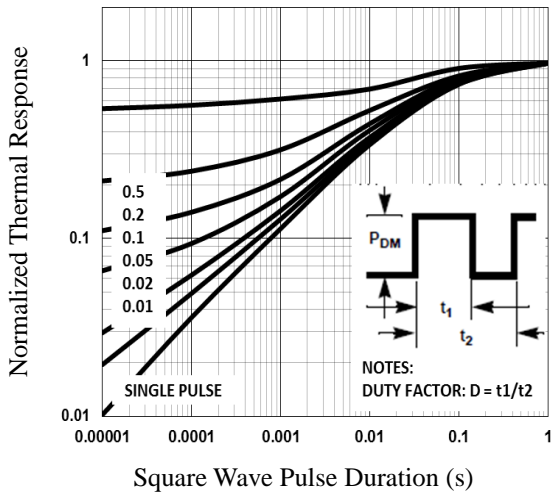


Fig.7 Normalized Transient Impedance

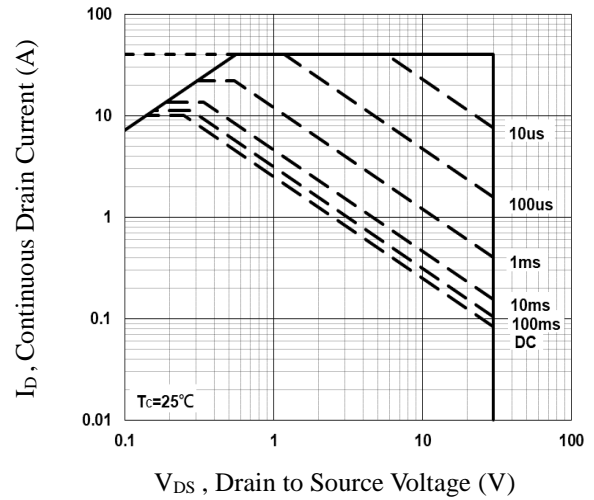


Fig.8 Maximum Safe Operation Area

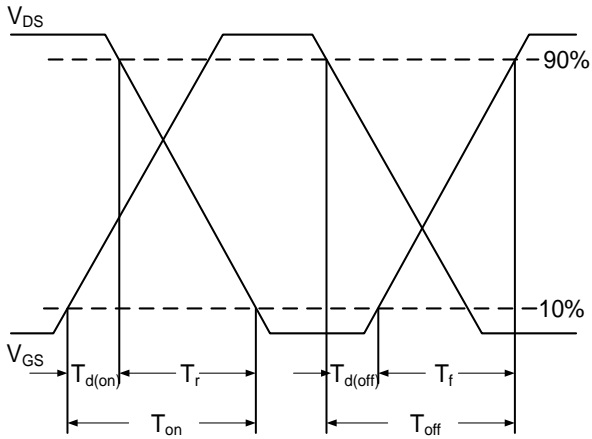


Fig.9 Switching Time Waveform

P-CH Electrical Characteristics (T_J=25 °C, unless otherwise)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-30V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =125°C	---	---	-10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-6A	---	30	36	mΩ
		V _{GS} =-4.5V, I _D =-5A	---	44	57	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.6	-2.5	V
g _{fs}	Forward Transconductance	V _{DS} =-10V, I _D =-3A	---	5	---	S

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{4, 5}	V _{DS} =-15V, V _{GS} =-10V, I _D =-3A	---	11	17	nC
Q _{gs}	Gate-Source Charge ^{4, 5}		---	1.5	2.5	
Q _{gd}	Gate-Drain Charge ^{4, 5}		---	2.5	4	
T _{d(on)}	Turn-On Delay Time ^{4, 5}	V _{DD} =-15V, V _{GS} =-10V, R _G =6Ω I _D =-3A	---	4	6	ns
T _r	Rise Time ^{4, 5}		---	12.8	20	
T _{d(off)}	Turn-Off Delay Time ^{4, 5}		---	23	35	
T _f	Fall Time ^{4, 5}		---	6.7	10	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, F=1MHz	---	800	1200	pF
C _{oss}	Output Capacitance		---	110	165	
C _{rss}	Reverse Transfer Capacitance		---	75	115	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	---	19	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	-6	A
I _{SM}	Pulsed Source Current		---	---	-12	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1	V
T _{rr}	Reverse Recovery Time	V _R =30V, I _S =2A	---	200	---	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs, T _J =25°C	---	220	---	nC

Note :

4. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
5. Essentially independent of operating temperature.

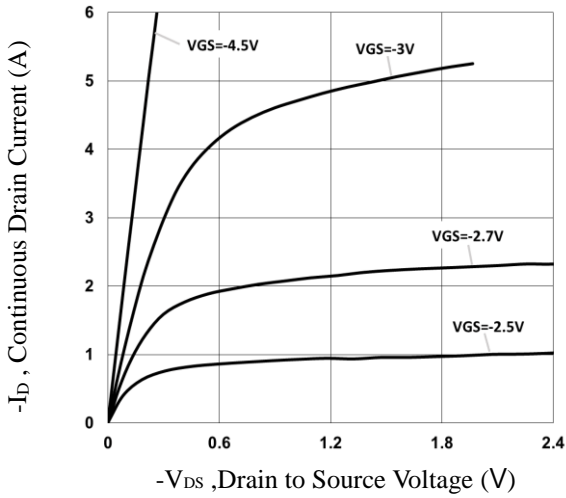


Fig.1 Typical Output Characteristics

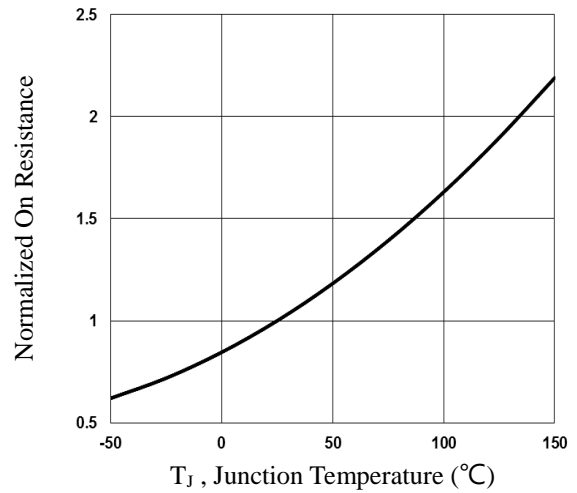


Fig.2 Normalized R_DS(on) vs. T_J

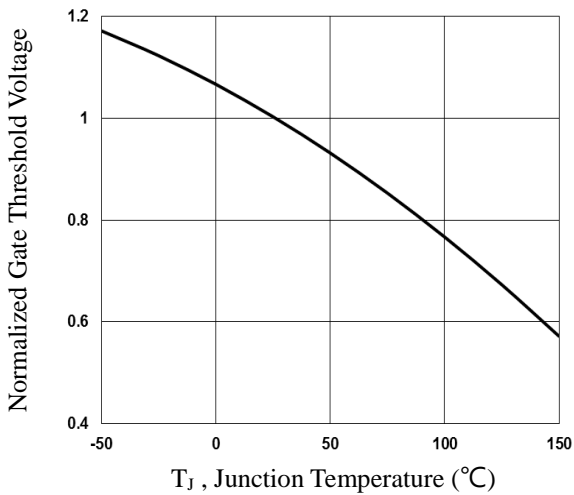


Fig.3 Normalized V_{th} vs. T_J

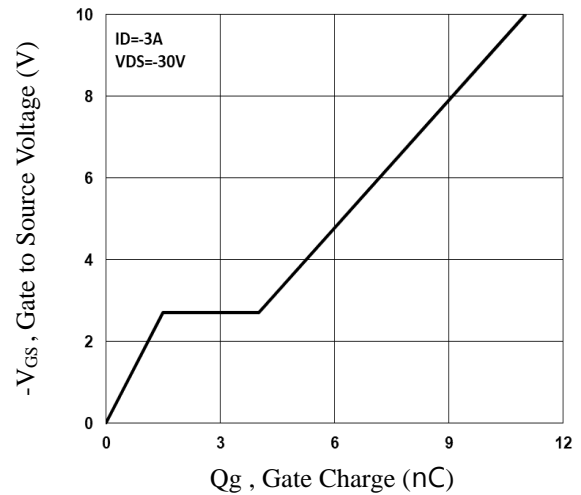


Fig.4 Gate Charge Waveform

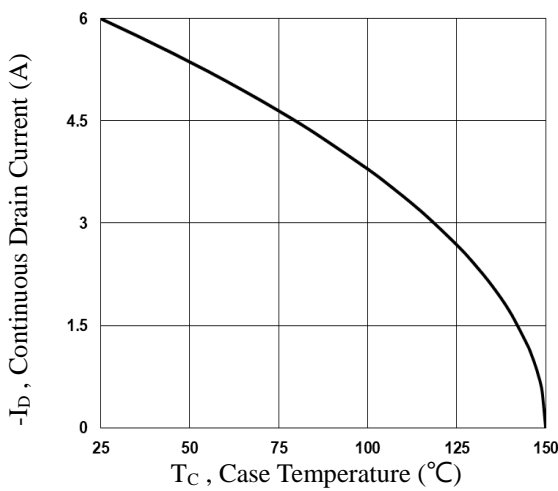


Fig.5 Continuous Drain Current vs. T_c

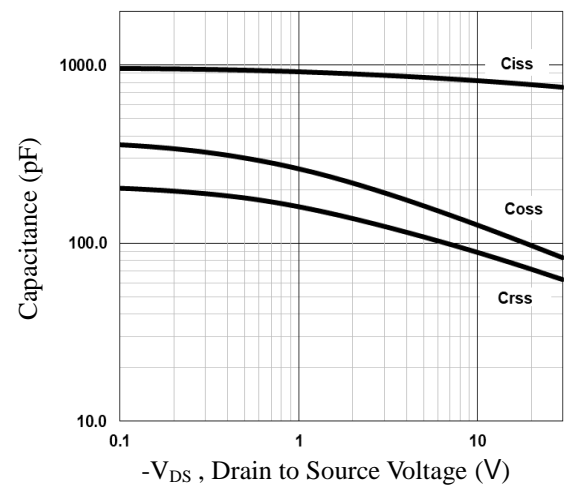


Fig.6 Capacitance Characteristics

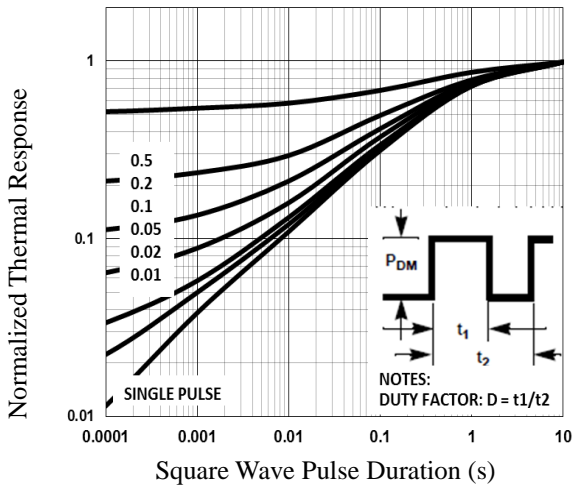


Fig.7 Normalized Transient Impedance

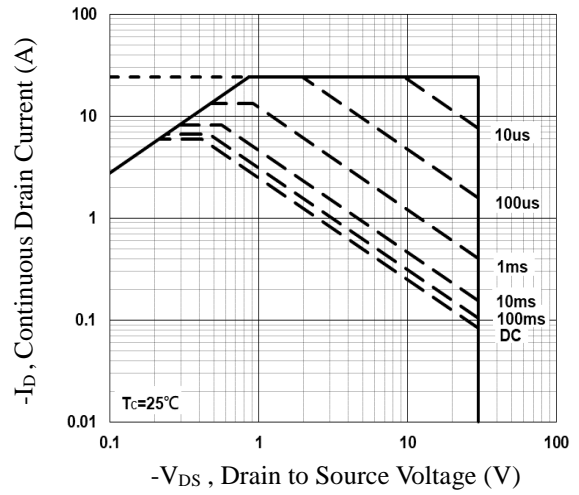


Fig.8 Maximum Safe Operation Area

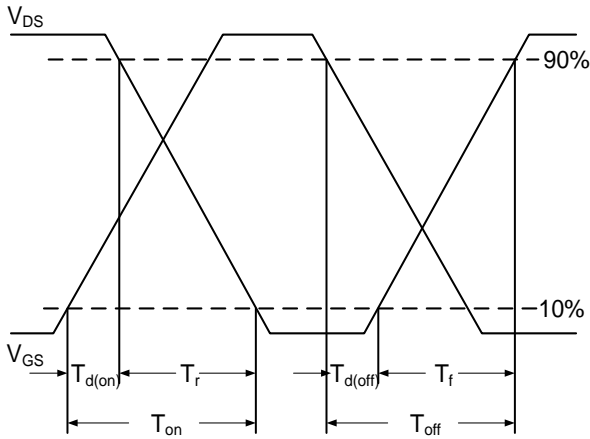
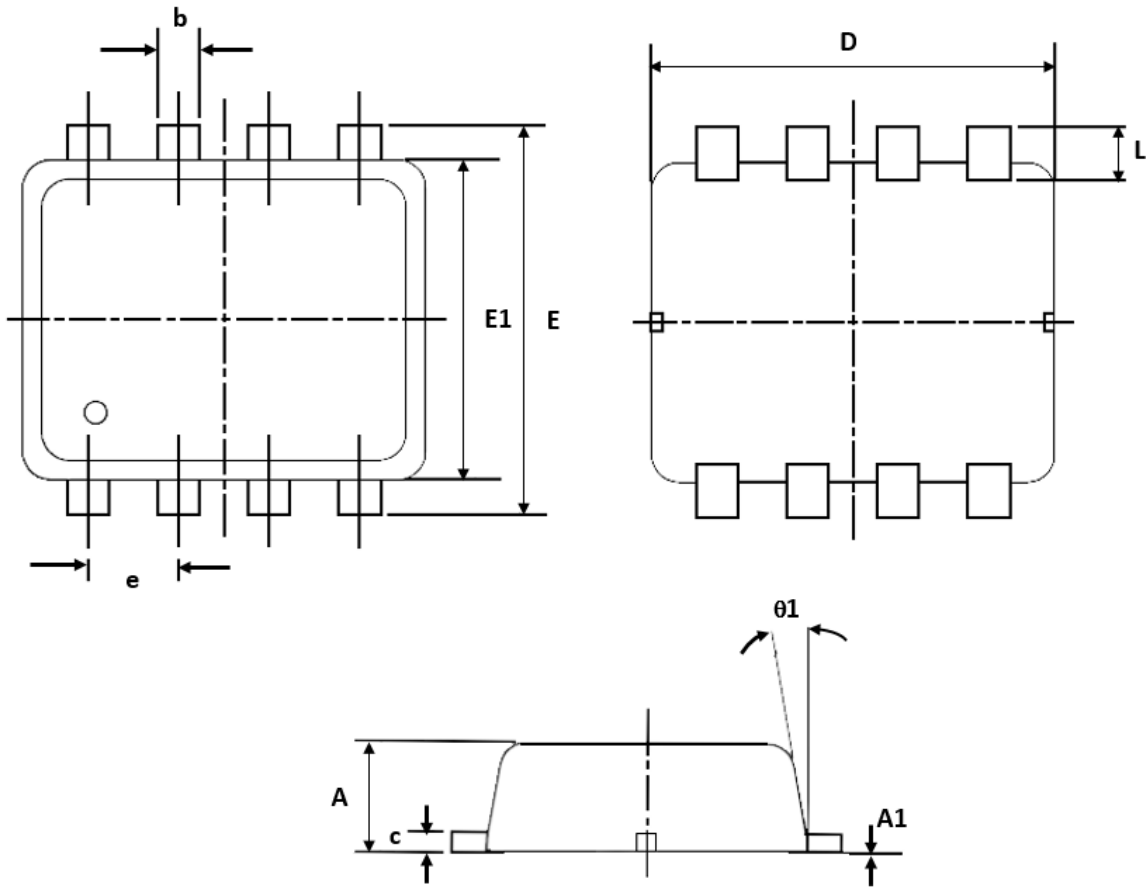


Fig.9 Switching Time Waveform

PPAK2.8x2.9 Dual NEP PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.900	0.028	0.035
A1	0.000	0.050	0.000	0.002
b	0.240	0.350	0.009	0.014
c	0.080	0.250	0.003	0.010
D	2.800	3.000	0.110	0.118
E	2.700	2.900	0.106	0.114
E1	2.200	2.400	0.087	0.095
e	0.65 BSC		0.026 BSC	
L	0.200	0.450	0.008	0.018
θ	12°	0°	12°	0°